

Serial No. 10/747,723  
Response to OA dated 10/25/05

**IN THE CLAIMS:**

1-3. (Canceled)

4. (Currently Amended) A method of operating a CMP system, comprising:  
obtaining a sensor signal from an electric drive assembly driving a pad conditioner of  
said CMP system; [[and]]  
estimating a condition of said pad conditioner on the basis of said sensor signal; and  
predicting a remaining lifetime of the conditioning surface of said pad conditioner on the  
basis of the estimated condition.

5. (Original) The method of claim 4, wherein said sensor signal is indicative of at  
least one of a revolution of at least one electric motor of said drive assembly and a torque of said  
at least one motor.

6. (Original) The method of claim 5, wherein estimating said condition of said pad  
conditioner includes:

establishing reference data for at least one characteristic of said pad conditioner; and  
comparing said sensor signal with said reference data.

7. (Original) The method of claim 6, wherein said at least one characteristic includes  
a frictional force acting between a conditioning surface of said pad conditioner and a polishing  
pad during operation of said CMP system.

Serial No. 10/747,723  
Response to OA dated 10/25/05

8. (Canceled)

9. (Original) The method of claim 4, further comprising controlling operation of said CMP system on the basis of said sensor signal.

10. (Original) The method of claim 9, wherein controlling operation of said CMP system includes readjusting at least one of a downforce, a polish time and a relative speed between a substrate and a polishing pad on the basis of said sensor signal.

11. (Original) The method of claim 9, wherein controlling operation of said CMP system includes readjusting a drive signal to said drive assembly on the basis of said sensor signal to adjust a conditioning effect.

12. (Currently Amended) A method of controlling a process sequence including a CMP process, comprising:

obtaining a signal from a conditioner drive assembly of a CMP system, said signal being indicative of at least one of a motor torque and a speed of a motor of said drive assembly; [[and]]

adjusting at least one process parameter in said process sequence on the basis of said signal; and

estimating a remaining lifetime of at least one consumable component of said CMP system on the basis of said signal.

Serial No. 10/747,723  
Response to OA dated 10/25/05

13. (Original) The method of claim 12, wherein said at least one process parameter includes at least one of a downforce, a polish time and relative speed of a pad and a polishing head in said CMP system.

14. (Original) The method of claim 12, wherein said at least one process parameter includes a deposition specific parameter of a deposition tool arranged upstream of said CMP system.

15-21. (Canceled)